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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	4224
Number of Logic Elements/Cells	-
Total RAM Bits	55296
Number of I/O	138
Number of Gates	250000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 70°C (TA)
Package / Case	256-LBGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ax250-2fg256

Axcelerator Family Device Status

Axcelerator® Devices	Status
AX125	Production
AX250	Production
AX500	Production
AX1000	Production
AX2000	Production

Temperature Grade Offerings

Package	AX125	AX250	AX500	AX1000	AX2000
PQ208	–	C, I, M	C, I, M	–	–
CQ208	–	M	M	–	–
CQ256	–	–	–	–	M
FG256	C, I	C, I, M	–	–	–
FG324	C, I	–	–	–	–
CQ352	–	M	M	M	M
FG484	–	C, I, M	C, I, M	C, I, M	–
CG624	–	–	–	M	M
FG676	–	–	C, I, M	C, I, M	–
BG729	–	–	–	C, I, M	–
FG896	–	–	–	C, I, M	C, I, M
FG1152	–	–	–	–	C, I, M

C = Commercial

I = Industrial

M = Military

Speed Grade and Temperature Grade Matrix

Temperature Grade	Std	–1	–2
C	✓	✓	✓
I	✓	✓	✓
M	✓	✓	–

C = Commercial

I = Industrial

M = Military

The maximum power dissipation allowed for Military temperature and Mil-Std 883B devices is specified as a function of θ_{jc}.

Table 2-6 • **Package Thermal Characteristics**

Package Type	Pin Count	θ_{jc}	θ_{ja} Still Air	θ_{ja} 1.0m/s	θ_{ja} 2.5m/s	Units
Chip Scale Package (CSP)	180	N/A	57.8	51.0	50	°C/W
Plastic Quad Flat Pack (PQFP)	208	8.0	26	23.5	20.9	°C/W
Plastic Ball Grid Array (PBGA)	729	2.2	13.7	10.6	9.6	°C/W
Fine Pitch Ball Grid Array (FBGA)	256	3.0	26.6	22.8	21.5	°C/W
Fine Pitch Ball Grid Array (FBGA)	324	3.0	25.8	22.1	20.9	°C/W
Fine Pitch Ball Grid Array (FBGA)	484	3.2	20.5	17.0	15.9	°C/W
Fine Pitch Ball Grid Array (FBGA)	676	3.2	16.4	13.0	12.0	°C/W
Fine Pitch Ball Grid Array (FBGA)	896	2.4	13.6	10.4	9.4	°C/W
Fine Pitch Ball Grid Array (FBGA)	1152	1.8	12.0	8.9	7.9	°C/W
Ceramic Quad Flat Pack (CQFP)[1]	208	2.0	22	19.8	18.0	°C/W
Ceramic Quad Flat Pack (CQFP)[1]	352	2.0	17.9	16.1	14.7	°C/W
Ceramic Column Grid Array (CCGA)[2]	624	6.5	8.9	8.5	8	°C/W

Notes:

1. *θ_{jc} for the 208-pin and 352-pin CQFP refers to the thermal resistance between the junction and the bottom of the package.*
2. *θ_{jc} for the 624-pin CCGA refers to the thermal resistance between the junction and the top surface of the package. Thermal resistance from junction to board (θ_{jb}) for CCGA 624 package is 3.4°C/W.*

Timing Characteristics

Axcelerator devices are manufactured in a CMOS process, therefore, device performance varies according to temperature, voltage, and process variations. Minimum timing parameters reflect maximum operating voltage, minimum operating temperature, and best-case processing. Maximum timing parameters reflect minimum operating voltage, maximum operating temperature, and worst-case processing. The derating factors shown in Table 2-7 should be applied to all timing data contained within this datasheet.

Table 2-7 • **Temperature and Voltage Timing Derating Factors (Normalized to Worst-Case Commercial, T_J = 70°C, VCCA = 1.425V)**

	Junction Temperature						
VCCA	–55°C	–40°C	0°C	25°C	70°C	85°C	125°C
1.4 V	0.83	0.86	0.91	0.96	1.02	1.05	1.15
1.425 V	0.82	0.84	0.90	0.94	1.00	1.04	1.13
1.5 V	0.78	0.80	0.85	0.89	0.95	0.98	1.07
1.575 V	0.74	0.76	0.81	0.85	0.90	0.94	1.02
1.6 V	0.73	0.75	0.80	0.84	0.89	0.92	1.01

Notes:

1. *The user can set the junction temperature in Designer software to be any integer value in the range of –55°C to 175°C.*
2. *The user can set the core voltage in Designer software to be any value between 1.4V and 1.6V.*

All timing numbers listed in this datasheet represent sample timing characteristics of Axcelerator devices. Actual timing delay values are design-specific and can be derived from the Timer tool in Microsemi's Designer software after place-and-route.

Using the Weak Pull-Up and Pull-Down Circuits

Each Axcelerator I/O comes with a weak pull-up/down circuit (on the order of 10 kΩ). These are weak transistors with the gates tied on, so the on resistance of the transistor emulates a resistor. The weak pull-up and pull-down is active only when the device is powered up, and they must be biased to be on. When the rails are coming up, they are not biased fully, so they do not behave as resistors until the voltage is at sufficient levels to bias the transistors. The key is they really are transistors; they are not traces of poly silicon, which is another way to do an on-chip resistor (those take much more room). I/O macros are provided for combinations of pull up/down for LVTTL, LVCMOS (2.5 V, 1.8 V, and 1.5 V) standards. These macros can be instantiated if a keeper circuit for any input buffer is required.

Customizing the I/O

- A five-bit programmable input delay element is associated with each I/O. The value of this delay is set on a bank-wide basis (Table 2-14). It is optional for each input buffer within the bank (i.e. the user can enable or disable the delay element for the I/O). When the input buffer drives a register within the I/O, the delay element is activated by default to ensure a zero hold-time. The default setting for this property can be set in Designer. When the input buffer does not drive a register, the delay element is deactivated to provide higher performance. Again, this can be overridden by changing the default setting for this property in Designer.
- The slew-rate value for the LVTTL output buffer can be programmed and can be set to either slow or fast.
- The drive strength value for LVTTL output buffers can be programmed as well. There are four different drive strength values – 8 mA, 12 mA, 16 mA, or 24 mA – that can be specified in Designer.[5]

Table 2-14 • **Bank-Wide Delay Values**

Bits Setting	Delay (ns)	Bits Setting	Delay (ns)
0	0.54	16	2.01
1	0.65	17	2.13
2	0.71	18	2.19
3	0.83	19	2.3
4	0.9	20	2.38
5	1.01	21	2.49
6	1.08	22	2.55
7	1.19	23	2.67
8	1.27	24	2.75
9	1.39	25	2.87
10	1.45	26	2.93
11	1.56	27	3.04
12	1.64	28	3.12
13	1.75	29	3.23
14	1.81	30	3.29
15	1.93	31	3.41

Note: Delay values are approximate and will vary with process, temperature, and voltage.

5. *These values are minimum drive strengths.*

***Table 2-40* • 3.3 V GTL+ I/O Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
3.3 V GTL+I/O Module Timing								
t_{DP}	Input Buffer		1.71		1.95		2.29	ns
t_{PY}	Output Buffer		1.13		1.29		1.52	ns
t_{ICLKQ}	Clock-to-Q for the I/O input register		0.67		0.77		0.90	ns
t_{OCLKQ}	Clock-to-Q for the I/O output register and the I/O enable register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

Class II

Table 2-47 • DC Input and Output Levels

VIL		VIH		VOL	VOH	IOL	IOH
Min., V	Max., V	Min., V	Max., V	Max., V	Min,. V	mA	mA
-0.3	VREF – 0.2	VREF + 0.2	3.6	VREF – 0.8	VREF + 0.8	15.2	-15.2

AC Loadings

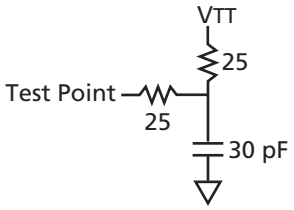


Figure 2-22 • AC Test Loads

Table 2-48 • AC Waveforms, Measuring Points, and Capacitive Loads

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C_{load} (pF)
VREF – 0.75	VREF + 0.75	VREF	1.25	30

*Note: * Measuring Point = V_{trip}*

Timing Characteristics

Table 2-49 • 2.5 V SSTL2 Class II I/O Module
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 2.3 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Units
2.5 V SSTL2 Class II I/O Module Timing								
t_{DP}	Input Buffer		1.89		2.16		2.53	ns
t_{PY}	Output Buffer		2.39		2.72		3.20	ns
t_{ICLKQ}	Clock-to-Q for the I/O input register		0.67		0.77		0.90	ns
t_{OCLKQ}	Clock-to-Q for the I/O output register and the I/O enable register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

single-ended, or voltage-referenced standard. The [H]CLKxN pad can only be used as a differential pair with [H]CLKxP.

The block marked “/i Delay Match” is a fixed delay equal to that of the i divider. The “/j Delay Match” block has the same function as its j divider counterpart.

Functional Description

Figure 2-48 on page 2-75 illustrates a block diagram of the PLL. The PLL contains two dividers, i and j, that allow frequency scaling of the clock signal:

- The i divider in the feedback path allows multiplication of the input clock by integer factors ranging from 1 to 64, and the resultant frequency is available at the output of the PLL block.
- The j divider divides the PLL output by integer factors ranging from 1 to 64, and the divided clock is available at CLK1.
- The two dividers together can implement any combination of multiplication and division up to a maximum frequency of 1 GHz on CLK1. Both the CLK1 and CLK2 outputs have a fixed 50/50 duty cycle.
- The output frequencies of the two clocks are given by the following formulas (f_{REF} is the reference clock frequency):

$$f_{CLK1} = f_{REF} * (DividerI) / (DividerJ)$$

EQ 4

$$f_{CLK2} = f_{REF} * (DividerI)$$

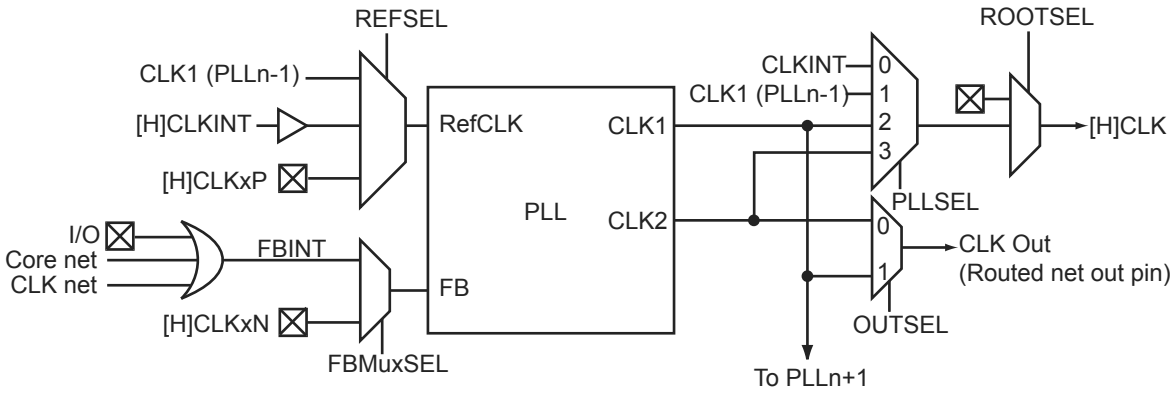
EQ 5

- CLK2 provides the PLL output directly—without division

The input and output frequency ranges are selected by LowFreq and Osc(2:0), respectively. These functions and their possible values are detailed in Table 2-80 on page 2-77.

The delay lines shown in Figure 2-48 on page 2-75 are programmable. The feedback clock path can be delayed (using the five DelayLine bits) relative to the reference clock (or vice versa) by up to 3.75 ns in increments of 250 ps. Table 2-80 on page 2-77 describes the usage of these bits. The delay increments are independent of frequency, so this results in phase changes that vary with frequency. The delay value is highly dependent on V_{CC} and the speed grade.

Figure 2-49 is a logical diagram of the various control signals to the PLL and shows how the PLL interfaces with the global and routing networks of the FPGA. Note that not all signals are user-accessible. These non-user-accessible signals are used by the place-and-route tool to control the configuration of the PLL. The user gains access to these control signals either based upon the connections built in the user's design or through the special macros (Table 2-84 on page 2-81) inserted into the design. For example, connecting the macro PLLOUT to CLK2 will control the OUTSEL signal.



Note: Not all signals are available to the user.

Figure 2-49 • **PLL Logical Interface**

CLK1 and CLK2

Both PLL outputs, CLK1 and CLK2, can be used to drive a global resource, an adjacent PLL RefCLK input, or a net in the FPGA core. Not all drive combinations are possible (Table 2-81).

***Table 2-81* • PLL General Connections Rules**

CLK1	CLK2
HCLK	HCLK
CLK	CLK
HCLK	Routed net output
Routed net output	HCLK
HCLK	NONE
NONE	HCLK
CLK	NONE
NONE	CLK

Note: The PLL outputs remain Low when REFCLK is constant (either Low or High).

Restrictions on CLK1 and CLK2

- When both are driving global resources, they must be driving the same *type* of global resource (i.e. either HCLK or CLK).
- Only one can drive a routed net at any given time.

Table 2-82 and Table 2-83 specify all the possible CLK1 and CLK2 connections for the north and south PLLs. HCLK1 and HCLK2 are used to denote the different HCLK networks when two are being driven at the same time by a single PLL (Note that HCLK1 is the primary clock resource associated with the PLL, and HCLK2 is the clock resource associated with the adjacent PLL). Likewise, CLK1 and CLK2 are used to denote the different CLK networks when two are being driven at the same time by a single PLL (Figure 2-48 on page 2-75).

***Table 2-82* • North PLL Connections**

CLK1	CLK2
HCLK1	Routed net
HCLK1	Unused
HCLK2	HCLK1
HCLK2	Routed net
HCLK2	Both HCLK1 and routed net
HCLK2	Unused
Unused	HCLK1
Unused	Routed net
Unused	Both HCLK1 and routed net
Unused	Unused
Routed net	HCLK1
Routed net	Unused
Both HCLK1 and HCLK2	Routed net
Both HCLK1 and HCLK2	Unused
Both HCLK1 and routed net	Unusable
Both HCLK2 and routed net	HCLK1
Both HCLK2 and routed net	Unused
HCLK1, HCLK2, and routed net	Unusable

Note: Designer software currently does not support all of these connections. Only exclusive connections where one output connects to a single net are supported at this time (e.g.CLK1 driving HCLK1, and HCLK2 is not supported).

***Table 2-83* • South PLL Connections**

CLK1	CLK2
CLK1	Routed net
CLK1	Unused
CLK2	CLK1
CLK2	Routed net
CLK2	Both CLK1 and routed net
CLK2	Unused
Unused	CLK1
Unused	Routed net
Unused	Both CLK1 and routed net
Unused	Unused
Routed net	CLK1
Routed net	Unused
Both CLK1 and CLK2	Routed net
Both CLK1 and CLK2	Unused
Both CLK1 and routed net	Unusable
Both CLK2 and routed net	CLK1
Both CLK2 and routed net	Unused
CLK1, CLK2, and routed net	Unusable

Note: Designer software currently does not support all of these connections. Only exclusive connections where one output connects to a single net are supported at this time (e.g., CLK1 driving both CLK1 and CLK2 is not supported).

***Table 2-90* • Two RAM Blocks Cascaded**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
Write Mode								
t_{WDASU}	Write Data Setup vs. WCLK		1.39		1.59		1.87	ns
t_{WDAHD}	Write Data Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WADSU}	Write Address Setup vs. WCLK		1.39		1.59		1.87	ns
t_{WADHD}	Write Address Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WENSU}	Write Enable Setup vs. WCLK		1.39		1.59		1.87	ns
t_{WENHD}	Write Enable Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WCKH}	WCLK Minimum High Pulse Width	0.75		0.75		0.75		ns
t_{WCLK}	WCLK Minimum Low Pulse Width	1.76		1.76		1.76		ns
t_{WCKP}	WCLK Minimum Period	2.51		2.51		2.51		ns
Read Mode								
t_{RADSU}	Read Address Setup vs. RCLK		1.71		1.94		2.28	ns
t_{RADHD}	Read Address Hold vs. RCLK		0.00		0.00		0.00	ns
t_{RENSU}	Read Enable Setup vs. RCLK		1.71		1.94		2.28	ns
t_{RENHD}	Read Enable Hold vs. RCLK		0.00		0.00		0.00	ns
$t_{RCK2RD1}$	RCLK-To-OUT (Pipelined)		1.43		1.63		1.92	ns
$t_{RCK2RD2}$	RCLK-To-OUT (Non-Pipelined)		2.26		2.58		3.03	ns
t_{RCLKH}	RCLK Minimum High Pulse Width	0.73		0.73		0.73		ns
t_{RCLKL}	RCLK Minimum Low Pulse Width	1.89		1.89		1.89		ns
t_{RCKP}	RCLK Minimum Period	2.62		2.62		2.62		ns

Note: Timing data for these two cascaded RAM blocks uses a depth of 8,192. For all other combinations, use Microsemi's timing software.

***Table 2-93* • Sixteen RAM Blocks Cascaded**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
Write Mode								
t_{WDASU}	Write Data Setup vs. WCLK		16.54		18.84		22.15	ns
t_{WDAHD}	Write Data Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WADSU}	Write Address Setup vs. WCLK		16.54		18.84		22.15	ns
t_{WADHD}	Write Address Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WENSU}	Write Enable Setup vs. WCLK		16.54		18.84		22.15	ns
t_{WENHD}	Write Enable Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WCKH}	WCLK Minimum High Pulse Width	0.75		0.75		0.75		ns
t_{WCLK}	WCLK Minimum Low Pulse Width	13.40		13.40		13.40		ns
t_{WCKP}	WCLK Minimum Period	14.15		14.15		14.15		ns
Read Mode								
t_{RADSU}	Read Address Setup vs. RCLK		18.13		20.65		24.27	ns
t_{RADHD}	Read Address Hold vs. RCLK		0.00		0.00		0.00	ns
t_{RENSU}	Read Enable Setup vs. RCLK		18.13		20.65		24.27	ns
t_{RENHD}	Read Enable Hold vs. RCLK		0.00		0.00		0.00	ns
$t_{RCK2RD1}$	RCLK-To-OUT (Pipelined)		12.08		13.76		16.17	ns
$t_{RCK2RD2}$	RCLK-To-OUT (Non-Pipelined)		12.83		14.62		17.18	ns
t_{RCLKH}	RCLK Minimum High Pulse Width	0.73		0.73		0.73		ns
t_{RCLKL}	RCLK Minimum Low Pulse Width	14.41		14.41		14.41		ns
t_{RCKP}	RCLK Minimum Period	15.14		15.14		15.14		ns

Note: Timing data for these sixteen cascaded RAM blocks uses a depth of 65,536. For all other combinations, use Microsemi's timing software.

Figure 2-63 illustrates flag generation.

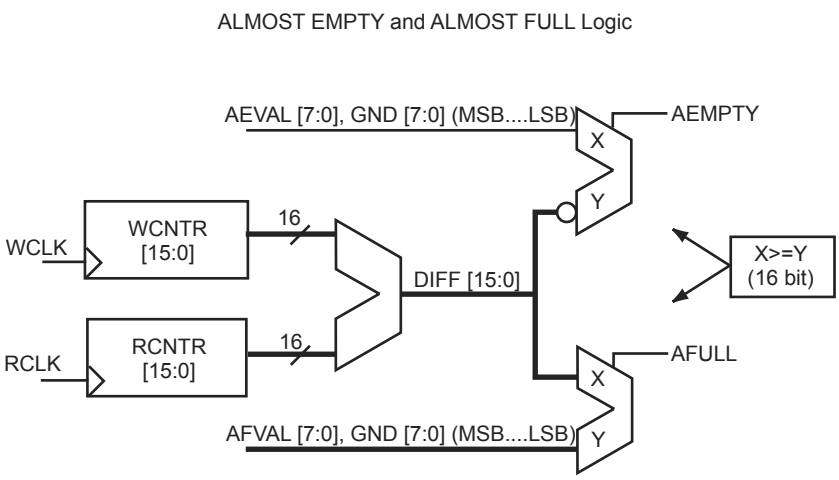


Figure 2-63 • **ALMOST-EMPTY and ALMOST-FULL Logic**

The Verilog codes for the flags are:

```
assign AF = (DIFF[15:0] >={AFVAL[7:0],8'b00000000})?1:0;
assign AE = ({AEVAL[7:0],8'b00000000}>=DIFF[15:0])?1:0;
```

The number of DIFF-bits active depends on the configuration depth and width (Table 2-95).

Table 2-95 • **Number of Available Configuration Bits**

Number of Blocks	Block DxW	Number of AEVAL/AFVAL Bits
1	1x1	4
2	1x2	4
2	2x1	5
4	1x4	4
4	2x2	5
4	4x1	6
8	1x8	4
8	2x4	5
8	4x2	6
8	8x1	7
16	1x16	4
16	2x8	5
16	4x4	6
16	8x2	7
16	16x1	8

The active-high CLR pin is used to reset the FIFO to the empty state, which sets FULL and AFULL low, and EMPTY and AEMPTY high.

Assuming that the EMPTY flag is not set, new data is read from the FIFO when REN is valid on the active edge of the clock. Write and read transfers are described with timing requirements in "Timing Characteristics" on page 2-100.

throughout the fabric of the device and may be programmed by the user to thwart attempts to reverse engineer the device by attempting to exploit either the programming or probing interfaces. Both invasive and noninvasive attacks against an Axcelerator device that access or bypass these security fuses will destroy access to the rest of the device. (refer to the *Design Security in Nonvolatile Flash and Antifuse FPGAs* white paper).

Look for this symbol to ensure your valuable IP is protected with highest level of security in the industry.

Figure 2-69 • **FuseLock Logo**

To ensure maximum security in Axcelerator devices, it is recommended that the user program the device security fuse (SFUS). When programmed, the Silicon Explorer II testing probes are disabled to prevent internal probing, and the programming interface is also disabled. All JTAG public instructions are still accessible by the user.

For more information, refer to the *Implementation of Security in Actel Antifuse FPGAs* application note.

Global Set Fuse

The Global Set Fuse determines if all R-cells and I/O registers (InReg, OutReg, and EnReg) are either cleared or preset by driving the GCLR and GPSET inputs of all R-cells and I/O Registers (Figure 2-31 on page 2-58). Default setting is to clear all registers (GCLR = 0 and GPSET =1) at device power-up. When the GBSETFUS option is checked during FUSE file generation, all registers are preset (GCLR = 1 and GPSET= 0). A local CLR or PRESET will take precedence over this setting. Both pins are pulled High during normal device operation. For use details, see the Libero IDE online help.

Silicon Explorer II Probe Interface

Silicon Explorer II is an integrated hardware and software solution that, in conjunction with the Designer tools, allows users to examine any of the internal nets (except I/O registers) of the device while it is operating in a prototype or a production system. The user can probe up to four nodes at a time without changing the placement and routing of the design and without using any additional device resources. Highlighted nets in Designer's ChipPlanner can be accessed using Silicon Explorer II in order to observe their real time values.

Silicon Explorer II's noninvasive method does not alter timing or loading effects, thus shortening the debug cycle. In addition, Silicon Explorer II does not require relayout or additional MUXes to bring signals out to external pins, which is necessary when using programmable logic devices from other suppliers. By eliminating multiple place-and-route program cycles, the integrity of the design is maintained throughout the debug process.

Each member of the Axcelerator family has four external pads: PRA, PRB, PRC, and PRD. These can be used to bring out four probe signals from the Axcelerator device (note that the AX125 only has two probe signals that can be observed: PRA and PRB). Each core tile has up to two probe signals. To disallow probing, the SFUS security fuse in the silicon signature has to be programmed (see "Special Fuses" on page 2-108).

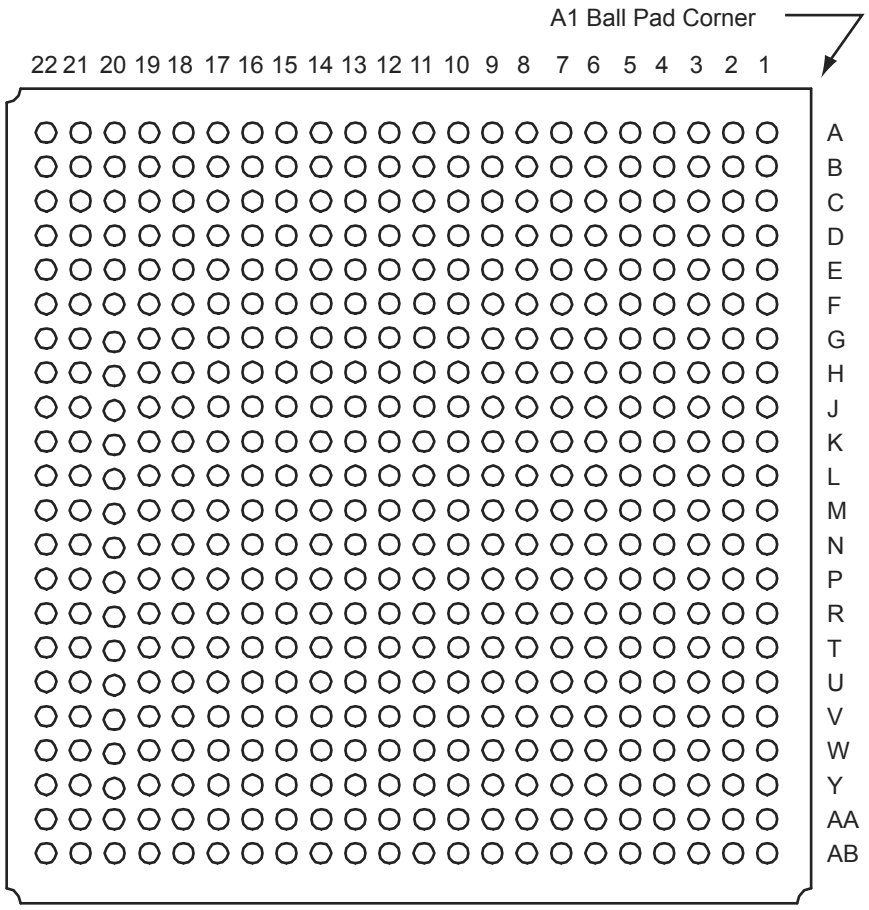
Silicon Explorer II connects to the host PC using a standard serial port connector. Connections to the circuit board are achieved using a nine-pin D-Sub connector (Figure 1-9 on page 1-7). Once the design has been placed-and-routed, and the Axcelerator device has been programmed, Silicon Explorer II can be connected and the Explorer software can be launched.

Silicon Explorer II comes with an additional optional PC hosted tool that emulates an 18-channel logic analyzer. Four channels are used to monitor four internal nodes, and 14 channels are available to probe external signals. The software included with the tool provides the user with an intuitive interface that allows for easy viewing and editing of signal waveforms.

FG256-Pin FBGA	
AX125 Function	**Pin Number**
VCCA	L10
VCCA	L7
VCCA	L8
VCCA	L9
VCCA	N3
VCCA	P14
VCCPLA	C7
VCCPLB	D6
VCCPLC	A10
VCCPLD	D10
VCCPLE	P10
VCCPLF	N11
VCCPLG	T7
VCCPLH	N7
VCCDA	A2
VCCDA	C13
VCCDA	D9
V_{CCDA}	H1
VCCDA	J15
VCCDA	N14
VCCDA	N8
VCCDA	P4
VCCIB0	E6
VCCIB0	E7
VCCIB0	E8
VCCIB1	E10
VCCIB1	E11
VCCIB1	E9
VCCIB2	F12
VCCIB2	G12
VCCIB2	H12
VCCIB3	J12
VCCIB3	K12
VCCIB3	L12
VCCIB4	M10

FG256-Pin FBGA	
AX125 Function	**Pin Number**
VCCIB4	M11
VCCIB4	M9
VCCIB5	M6
VCCIB5	M7
VCCIB5	M8
VCCIB6	J5
VCCIB6	K5
VCCIB6	L5
VCCIB7	F5
VCCIB7	G5
VCCIB7	H5
VCOMPLA	A7
VCOMPLB	D7
VCOMPLC	B9
VCOMPLD	D11
VCOMPLE	T10
VCOMPLF	N10
VCOMPLG	R8
VCOMPLH	N6
VPUMP	A14

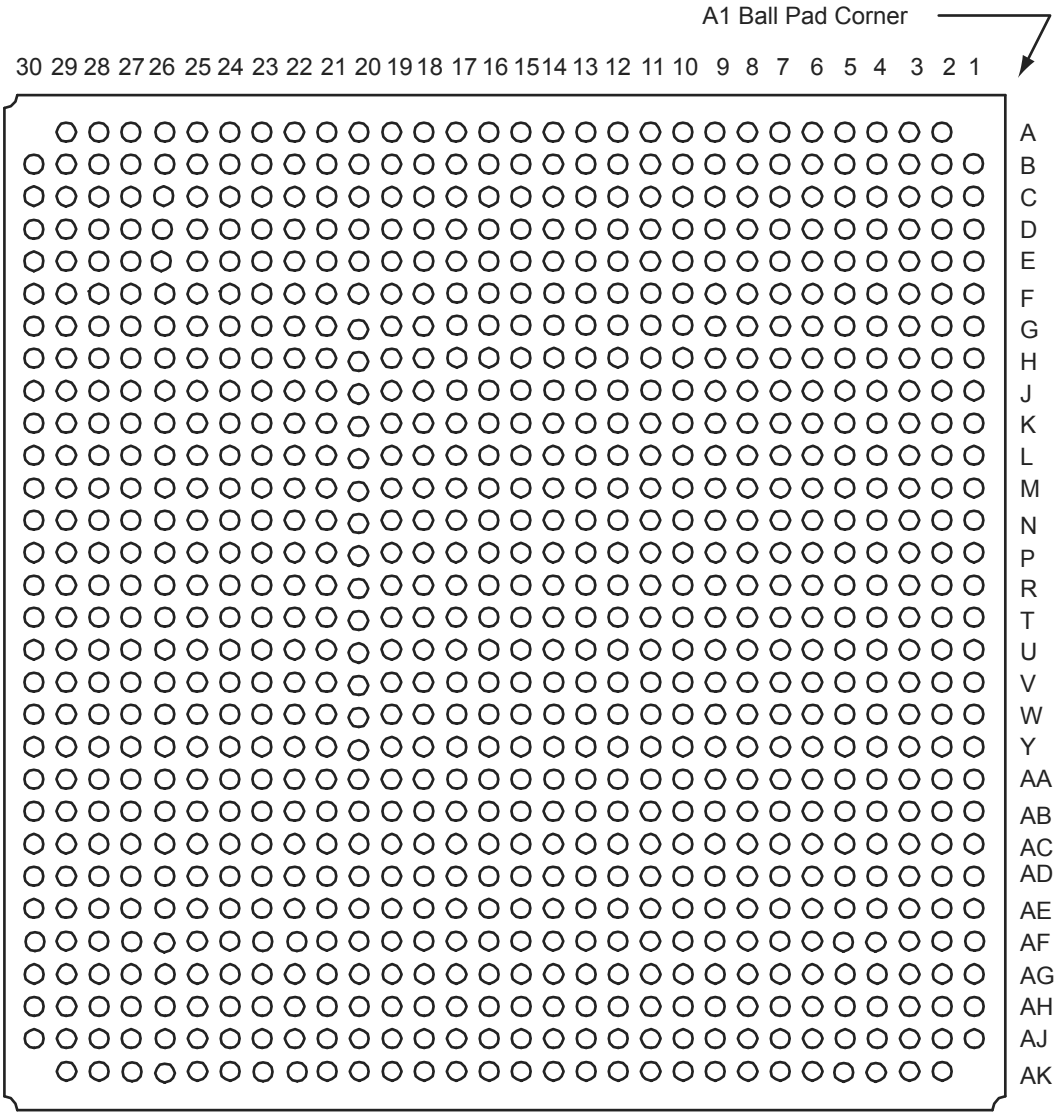
FG484



Note

For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

FG896



Note

For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

FG896	
AX2000 Function	Pin Number
IO245PB5F23	AG8
IO246NB5F23	AD8
IO246PB5F23	AD9
IO247NB5F23	AG7
IO247PB5F23	AH7
IO248NB5F23	AK5
IO249NB5F23	AJ5
IO249PB5F23	AJ6
IO250NB5F23	AC8
IO250PB5F23	AC9
IO251NB5F23	AH6
IO251PB5F23	AG6
IO252NB5F23	AF6
IO252PB5F23	AF7
IO253NB5F23	AG2
IO253PB5F23	AG1
IO254NB5F23	AE7
IO254PB5F23	AE8
IO255NB5F23	AG5
IO255PB5F23	AH5
IO256NB5F23	AJ4
IO256PB5F23	AK4
Bank 6	
IO257NB6F24	AE4
IO257PB6F24	AF4
IO258NB6F24	AB7
IO258PB6F24	AC7
IO259NB6F24	AD5
IO259PB6F24	AE5
IO260NB6F24	AF1
IO260PB6F24	AF2
IO261NB6F24	AF3
IO261PB6F24	AG3
IO262NB6F24	AC4
IO262PB6F24	AD4

FG896	
AX2000 Function	Pin Number
IO263NB6F24	AD3
IO263PB6F24	AE3
IO264NB6F24	AB6
IO264PB6F24	AC6
IO265NB6F24	AD1
IO265PB6F24	AE1
IO266NB6F24	AA8
IO266PB6F24	AB8
IO267NB6F25	AB5
IO267PB6F25	AC5
IO268NB6F25	AB3
IO268PB6F25	AC3
IO269NB6F25	AC2
IO269PB6F25	AD2
IO270NB6F25	Y7
IO270PB6F25	AA7
IO271NB6F25	AA4
IO271PB6F25	AB4
IO272NB6F25	Y6
IO272PB6F25	AA6
IO273NB6F25	AB1*
IO273PB6F25	AE2*
IO274NB6F25	W8
IO274PB6F25	Y8
IO275NB6F25	Y5
IO275PB6F25	AA5
IO277NB6F25	AA2
IO277PB6F25	AA1
IO278NB6F26	W6
IO278PB6F26	W7
IO279NB6F26	Y3
IO279PB6F26	Y4
IO280NB6F26	V8
IO280PB6F26	V9
IO281NB6F26	Y1

FG896	
AX2000 Function	Pin Number
IO281PB6F26	Y2
IO282NB6F26	V5
IO282PB6F26	W5
IO284NB6F26	V7
IO284PB6F26	V6
IO285NB6F26	W3
IO285PB6F26	W4
IO286NB6F26	U8
IO286PB6F26	U9
IO287NB6F26	W1
IO287PB6F26	W2
IO288NB6F26	U7
IO288PB6F26	U6
IO290NB6F27	U4
IO290PB6F27	V4
IO291NB6F27	U3
IO291PB6F27	V3
IO292NB6F27	T5
IO292PB6F27	U5
IO293NB6F27	U2
IO293PB6F27	V2
IO294NB6F27	T8
IO294PB6F27	T9
IO296NB6F27	T1
IO296PB6F27	U1
IO298NB6F27	T7
IO298PB6F27	T6
IO299NB6F27	R2
IO299PB6F27	T2
Bank 7	
IO300NB7F28	R8
IO300PB7F28	R9
IO302NB7F28	R4
IO302PB7F28	R5
IO303NB7F28	P1

FG896	
AX2000 Function	Pin Number
VCCIB3	AH30
VCCIB3	T21
VCCIB3	U21
VCCIB3	V21
VCCIB3	W21
VCCIB3	W22
VCCIB3	Y21
VCCIB3	Y22
VCCIB4	AA16
VCCIB4	AA17
VCCIB4	AA18
VCCIB4	AA19
VCCIB4	AA20
VCCIB4	AB19
VCCIB4	AB20
VCCIB4	AB21
VCCIB4	AJ28
VCCIB4	AK28
VCCIB5	AA11
VCCIB5	AA12
VCCIB5	AA13
VCCIB5	AA14
VCCIB5	AA15
VCCIB5	AB10
VCCIB5	AB11
VCCIB5	AB12
VCCIB5	AJ3
VCCIB5	AK3
VCCIB6	AA9
VCCIB6	AH1
VCCIB6	AH2
VCCIB6	T10
VCCIB6	U10
VCCIB6	V10
VCCIB6	W10

FG896	
AX2000 Function	Pin Number
VCCIB6	W9
VCCIB6	Y10
VCCIB6	Y9
VCCIB7	C1
VCCIB7	C2
VCCIB7	K9
VCCIB7	L10
VCCIB7	L9
VCCIB7	M10
VCCIB7	M9
VCCIB7	N10
VCCIB7	P10
VCCIB7	R10
VCCPLA	G14
VCCPLB	H15
VCCPLC	G17
VCCPLD	J16
VCCPLE	AH17
VCCPLF	AC16
VCCPLG	AH14
VCCPLH	AD15
VCOMPLA	F14
VCOMPLB	J15
VCOMPLC	F17
VCOMPLD	H16
VCOMPLE	AF17
VCOMPLF	AD16
VCOMPLG	AF14
VCOMPLH	AB15
VPUMP	G24

PQ208	
AX250 Function	**Pin Number**
IO110PB7F7	19
IO112NB7F7	16
IO112PB7F7	17
IO117NB7F7	12
IO117PB7F7	13
IO119NB7F7	10
IO119PB7F7	11
IO121PB7F7	7
IO122NB7F7	5
IO122PB7F7	6
IO123NB7F7	3
IO123PB7F7	4
Dedicated I/O	
VCCDA	1
VCCDA	26
VCCDA	53
VCCDA	63
VCCDA	78
VCCDA	95
VCCDA	105
VCCDA	130
VCCDA	157
VCCDA	167
VCCDA	182
VCCDA	202
GND	104
GND	9
GND	15
GND	21
GND	32
GND	39
GND	46
GND	51
GND	59
GND	65
GND	69
GND	90

PQ208	
AX250 Function	**Pin Number**
GND	94
GND	99
GND	113
GND	119
GND	125
GND	136
GND	143
GND	150
GND	155
GND	164
GND	169
GND	173
GND	194
GND	196
GND	201
GND/LP	208
PRA	184
PRB	183
PRC	80
PRD	79
TCK	205
TDI	204
TDO	203
TMS	206
TRST	207
VCCA	2
VCCA	52
VCCA	156
VCCA	14
VCCA	38
VCCA	64
VCCA	93
VCCA	118
VCCA	142
VCCA	168
VCCA	195
VCCPLA	189

PQ208	
AX250 Function	**Pin Number**
VCCPLB	187
VCCPLC	178
VCCPLD	176
VCCPLE	85
VCCPLF	83
VCCPLG	74
VCCPLH	72
VCCIB0	193
VCCIB0	200
VCCIB1	163
VCCIB1	172
VCCIB2	135
VCCIB2	149
VCCIB3	112
VCCIB3	124
VCCIB4	89
VCCIB4	98
VCCIB5	58
VCCIB5	68
VCCIB6	31
VCCIB6	45
VCCIB7	8
VCCIB7	20
VCOMPLA	190
VCOMPLB	188
VCOMPLC	179
VCOMPLD	177
VCOMPLE	86
VCOMPLF	84
VCOMPLG	75
VCOMPLH	73
VPUMP	158

CQ352	
AX2000 Function	Pin Number
GND	21
GND	27
GND	33
GND	39
GND	45
GND	51
GND	57
GND	63
GND	69
GND	75
GND	81
GND	88
GND	89
GND	97
GND	103
GND	109
GND	115
GND	121
GND	133
GND	145
GND	151
GND	157
GND	163
GND	169
GND	176
GND	177
GND	186
GND	192
GND	198
GND	204
GND	210
GND	216
GND	222
GND	228
GND	234

CQ352	
AX2000 Function	Pin Number
GND	240
GND	246
GND	252
GND	258
GND	264
GND	265
GND	274
GND	280
GND	286
GND	292
GND	298
GND	310
GND	322
GND	330
GND	334
GND	340
GND	345
GND	352
PRA	312
PRB	311
PRC	135
PRD	134
TCK	349
TDI	348
TDO	347
TMS	350
TRST	351
VCCA	3
VCCA	14
VCCA	32
VCCA	56
VCCA	74
VCCA	87
VCCA	102
VCCA	114

CQ352	
AX2000 Function	Pin Number
VCCA	150
VCCA	162
VCCA	175
VCCA	191
VCCA	209
VCCA	233
VCCA	251
VCCA	263
VCCA	279
VCCA	291
VCCA	329
VCCA	339
VCCDA	2
VCCDA	44
VCCDA	90
VCCDA	91
VCCDA	116
VCCDA	117
VCCDA	130
VCCDA	131
VCCDA	132
VCCDA	148
VCCDA	149
VCCDA	174
VCCDA	178
VCCDA	221
VCCDA	266
VCCDA	268
VCCDA	293
VCCDA	294
VCCDA	307
VCCDA	308
VCCDA	309
VCCDA	327
VCCDA	328

CG624	
AX1000 Function	Pin Number
IO194NB6F18	Y3
IO194PB6F18	AA3
IO195NB6F18	V6
IO195PB6F18	W4
IO197NB6F18	R5
IO197PB6F18	U3
IO198NB6F18	P6
IO199NB6F18	Y5
IO199PB6F18	W5
IO200NB6F18	V3
IO200PB6F18	W3
IO201NB6F18	T7
IO201PB6F18	U7
IO202NB6F18	V2
IO203NB6F19	W2
IO203PB6F19	Y2
IO204NB6F19	AA1
IO204PB6F19	AB1
IO205NB6F19	R6
IO205PB6F19	T6
IO206NB6F19	W1
IO206PB6F19	Y1
IO207NB6F19	T2
IO207PB6F19	U2
IO208NB6F19	T1
IO208PB6F19	U1
IO209NB6F19	AA2
IO209PB6F19	AB2
IO210NB6F19	P5
IO211NB6F19	M1
IO211PB6F19	N1
IO212NB6F19	P1
IO212PB6F19	R1
IO213NB6F19	R8
IO213PB6F19	T8
IO215NB6F20	U4

CG624	
AX1000 Function	Pin Number
IO215PB6F20	V4
IO216NB6F20	P8
IO216PB6F20	R3
IO217NB6F20	P7
IO217PB6F20	R7
IO219NB6F20	R4
IO219PB6F20	T4
IO220NB6F20	P2
IO220PB6F20	R2
IO221NB6F20	N4
IO221PB6F20	P4
IO223NB6F20	M2
IO223PB6F20	N2
IO224NB6F20	N3
IO224PB6F20	P3
Bank 7	
IO225NB7F21	J2
IO225PB7F21	J1
IO226PB7F21	G2
IO227NB7F21	H3
IO227PB7F21	H2
IO229NB7F21	K2
IO229PB7F21	L2
IO230NB7F21	K1
IO230PB7F21	L1
IO231NB7F21	E2
IO231PB7F21	F2
IO232NB7F21	F1
IO232PB7F21	G1
IO233NB7F21	L3
IO233PB7F21	M3
IO234NB7F21	D1
IO234PB7F21	E1
IO235NB7F21	K4
IO235PB7F21	L4
IO236NB7F22	M6

CG624	
AX1000 Function	Pin Number
IO237NB7F22	N8
IO237PB7F22	N7
IO238NB7F22	M5
IO239NB7F22	L6
IO239PB7F22	L5
IO240NB7F22	M4
IO241NB7F22	L7
IO241PB7F22	M7
IO242NB7F22	J3
IO243NB7F22	M9
IO243PB7F22	M8
IO244NB7F22	P9
IO244PB7F22	N6
IO245NB7F22	K8
IO245PB7F22	L8
IO246NB7F22	F3
IO246PB7F22	E3
IO247NB7F23	K7
IO247PB7F23	K6
IO248NB7F23	D2
IO249NB7F23	G4
IO249PB7F23	G3
IO251NB7F23	N10
IO251PB7F23	N9
IO253NB7F23	H4
IO253PB7F23	J4
IO255NB7F23	J6
IO255PB7F23	J5
IO257NB7F23	H5
IO257PB7F23	H6
Dedicated I/O	
GND	K5
GND	A18
GND	A2
GND	A24
GND	A25